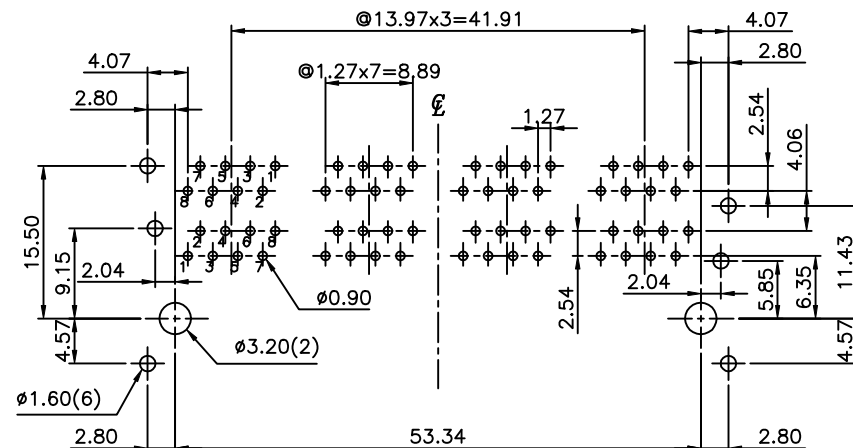
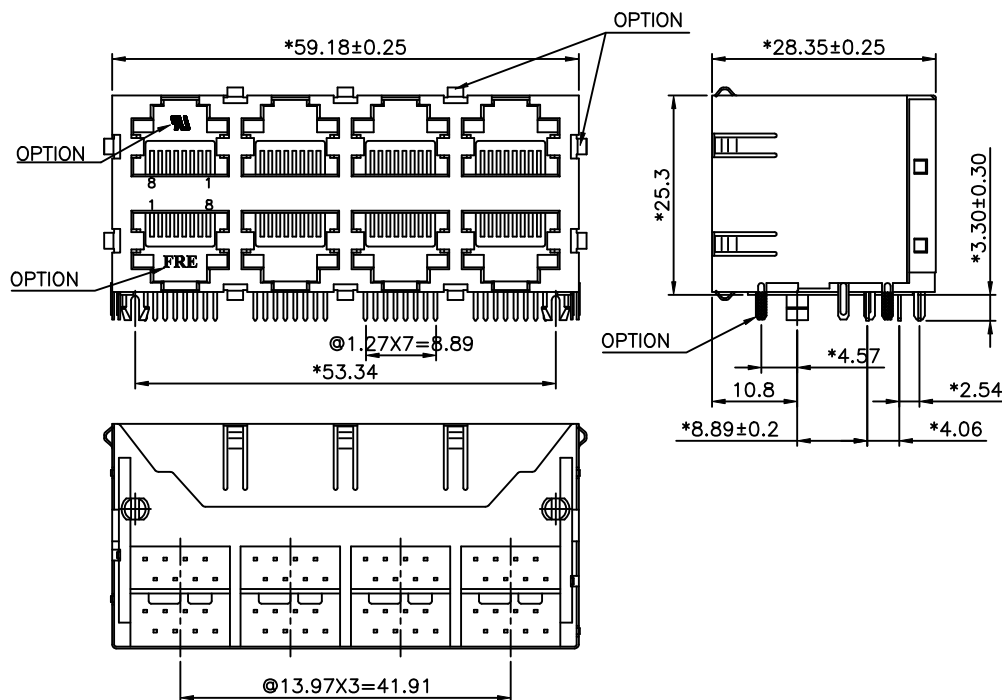


A1RFRD10

REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD
△		ADD P/N	JAM	
△		ADD P/N	JAM	



PC Board Layout Component Side Shown

Thickness=1.6mm

NOTES:

ELECTRICAL:

1. VOLTAGE RATING : 125 VAC RMS.
2. CURRENT RATING : 1.5 AMP.
3. CONTACT RESISTANCE : 50 MILLIOHMS MAX.
4. INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 500 VDC.
5. DIELECTRIC STRENGTH : 1000 VAC RMS 60Hz, 1MIN.

MECHANICAL:

1. HOUSING & INSERT MATERIAL : NYLON+30%.G.F UL94V-0.
2. CONTACT MATERIAL : PHOSPHOR BRONZE, t=0.35mm.
3. SHIELD MATERIAL : COPPER ALLOY, t=0.25mm.
4. PLATING : GOLD PLATING OVER NICKEL.
5. OPERATING LIFE : 750 CYCLES MIN.
6. PCB RETENTION PRE-SOLDER : 1 LB MIN.
7. PCB RETENTION POST-SOLDER: 10 LBS MIN.

ENVIRONMENTAL:

1. STORAGE : -40°C TO +85°C.
2. OPERATION: -40°C TO +85°C.

3. WAVE SOLDERING TEMPERATURE: 255~265°C (5~10 SECONDS)

MATES WITH MODULAR PLUG CONFORMING TO

FCC PART 68, SUBPART F.

CUL FILE NO. E163191

ROHS PART NUMBER: E5908-XXCXXX-L

- 1-W/O TABS
- 2-W/ TOP TABS
- 3-W/ SIDE TABS
- 4-W/ TOP&SIDE TABS
- 5-W/ TOP&BOTTOM&SIDE TABS

- 1- 3u" 2- 6u" 3-15u"
- 4-30u" 5-50u"

- 10-FRONT PEG 4.57,W/O PANEL STOP,W/O LOGO. △
- 15-FRONT PEG 4.57,W/O PANEL STOP,W/FRE&UL LOGO.
- 1E-FRONT PEG 4.57,W/O PANEL STOP,W/FRE W/O UL LOGO.

- T- Tin V- Nickel Q- GOLD
- J- W/NICKEL PLATED WITH TINNED GROUNDING PEG

DETACHED LISTS	MM (INCH)	DFTO YAN	DATE 04/27/05	FULL RISE ELECTRONIC CO., LTD	
	TOLERANCES EXCEPT AS NOTED	CHKD JAM	DATE 2005/09/08		
	MM	MFO	DATE		
	.0 ± 0.2 .00 ± 0.15 .000 ± 0.075	APPLY LUS	DATE 2005/09/08		
ANGLES ± 0.5		MATERIAL :		TITLE STAMPED PIN III	
THIRD ANGLE PROJECTION		QT'Y :		STACKED GANGED JACK, 2X4	
		FINISH :		DRAWING NO. GE593B51-LA	
		SCALE : 1.5 : 1		/PART NO. SEE NOTE	
		DO NOT SCALE DRAWING		SIZE A3	
				REV 2	
				SHEET 1 OF 1	

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